

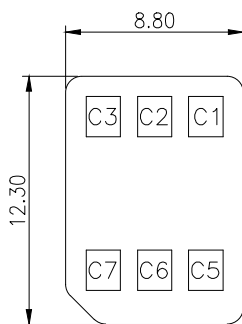
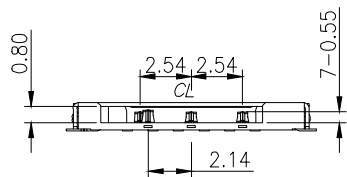
STEP 1 INSERT NANO SIM CARD



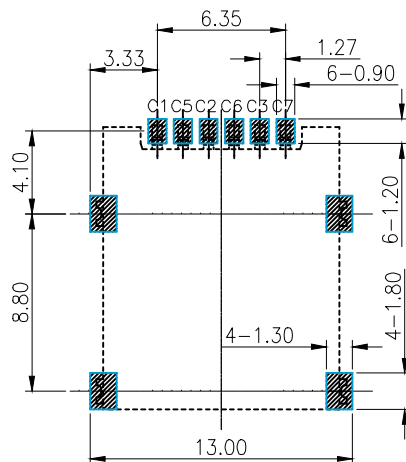
STEP 2 PUSH THE SHELL



STEP 3 FINISH



PIN NO.	PIN NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



RECOMMENDED PCB LAYOUT
TOLERANCE ± 0.05

■ SMT SOLDER AREA

NOTES:

1. MATERIAL:

- 1.1 Housing: High Temperature Thermoplastic UL94V-0; Color Black.
- 1.2 Terminal: Copper Alloy, $T=0.12\text{mm}$.
- 1.3 Shell: Stainless Steel, $T=0.20\text{mm}$.

2. FINISH:

- 2.1 Terminal: Plated Gold on the Contact Area and Solder Tails
- 2.2 Peg: Plated Gold on the Solder Tails.

3. SPECIALITY:

- 3.1 Rated current: 0.5A
- 3.2 Rated voltage: 50V
- 3.3 Contact Resistance: $80\text{m}\Omega$ MAX
- 3.4 Insulation Resistance: $100\text{M}\Omega$ MIN 100V DC
- 3.5 Dielectric withstanding voltage: 100V AC.
- 3.6 Solder ability: $245\pm 5^\circ\text{C}$, $5\pm 0.5\text{s}$.
- 3.7 Operating condition: Temperature: $-30^\circ\text{C}\sim +80^\circ\text{C}$
Humidity: 80% R.H MAX

深圳市迈瑞康电子有限公司

General	Angle	设计	16'/12/22
$X\pm 0.50$	$X^\circ\pm 2^\circ$	DESIGN	
$.X\pm 0.30$	$.X^\circ\pm 1^\circ$	校阅	
$.XX\pm 0.20$	$.XX^\circ\pm 0.5^\circ$	CHECK	16'/12/22
		承认	
		APPRO.	16'/12/22

TITLE:	NANO SIM 6PIN 掀盖1.4H		
PART NO.	MRK-SM00-140-0001		
FILE NAME.			
SCALE	1:1	UNIT:mm	A4 SHEET: 1 of 1

工程变更通知单号	版次	日期	新发行	说明	改变	承认
ECN(DCN) NO.	REV	DATE	DESCRIPTION	CHANGE	APPRO.	
	A	16'/12/22	新发行			